

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-299404

(43)Date of publication of application : 24.10.2000

(51)Int.Cl.

H01L 23/12

H05K 3/40

H05K 3/46

(21)Application number : 11-107757

(71)Applicant : SHINKO ELECTRIC IND CO LTD

(22)Date of filing : 15.04.1999

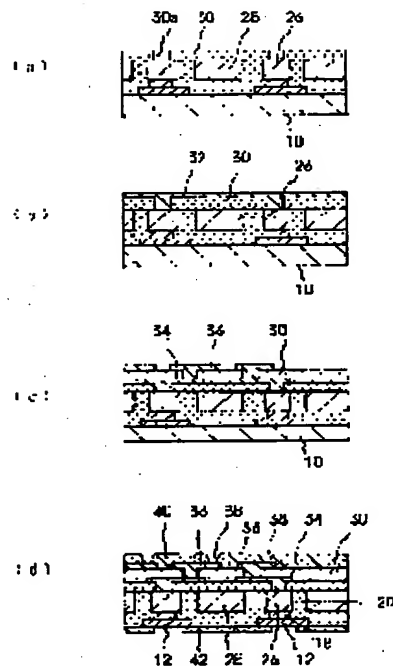
(72)Inventor : KOBAYASHI KAZUKI

## (54) MULTILAYER WIRING BOARD AND ITS MANUFACTURE

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a multilayer wiring board, in which a continuity part penetrating a core board can be formed with a high density and which is superior in thermal radiation and electrical characteristics.

**SOLUTION:** Wiring patterns 34 and 36 are formed on both sides or one side of a core board, and a continuity part penetrating the core board is connected electrically with the wiring pattern. In such a multilayer wiring board, the core board comprises of a conductor part, consisting of a via column 26 formed by plating and a conductor core part 28 and an insulator part 20 for electrically insulating the via column 26 and the conductor core part 28. After the wiring pattern is formed on the core board, the conductor board 10 is removed so as to obtain the multilayer board.



## LEGAL STATUS

[Date of request for examination]

01.05.2002

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

3592129

[Date of registration]

03.09.2004

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

BEST AVAILABLE COPY